

CP617-CM4957 PNP - RF Transistor Die 30mA, 25 Volt

The CP617-CM4957 is a silicon PNP RF transistor designed for high frequency amplifier and non-saturated switching applications.

		MECHANICA	L SPECIFICAT	IONS:		
(<u>60000</u> c		Die Size		15.7 x 15.7 MILS		
E B		Die Thickness		7.9 MILS		
		Base Bonding Pad Size		3.54 x 3.54 MILS		
		Emitter Bonding Pad Size		3.54 x 3.54 MILS		
		Top Side Metalization		AI – 9,000Å		
		Back Side Metalization		Au – 10,000Å		
		Scribe Alley Width		2.9 MILS		
		Wafer Diameter		4 INCHES		
BACKSIDE COLLECTOR R1 Gross Die Pe			r Wafer	44,140		
MAXIMUM RATINGS: (T _A =25°C)			SYMBOL			UNITS
Collector-Base Voltage			V _{CBO}	30		V
Collector-Emitter Voltage			VCEO	25		V
Emitter-Base Voltage			V _{EBO}	3.0		V
Continuous Collector Current			ΙC	30		mA
Continuous Base Current			۱ _B	2.0		А
Operating and Storage Junction Temperature			TJ, Tstg	-65 to +150		°C
ELECTRICA	L CHARACTERISTIC	CS : (T _A =25°C u	nless otherwise	e noted)		
SYMBOL I _{CBO}	SYMBOL TEST CONDITIONS		MIN	TYP	MAX 100	UNITS nA
BVCBO	I _C =100μΑ		30			V
BVCEO	I _C =1.0mA		25			V
BVEBO	I _E =100μΑ	3.0			V	
hFE	V _{CE} =10V, I _C =2.0n	nA	20		150	
h _{fe}	V _{CF} =10V, I _C =2.0n	nA, f=1.0kHz	20		200	
C _{cb}	V _{CB} =10V, I _E =0, f=		1.6	2.0	pF	
fT	V _{CF} =10V, I _C =2.0n	1200		2500	MHz	
G _{pe}	V _{CE} =10V, I _C =4.0n	17		25	dB	

MECHANICAL SPECIFICATIONS:

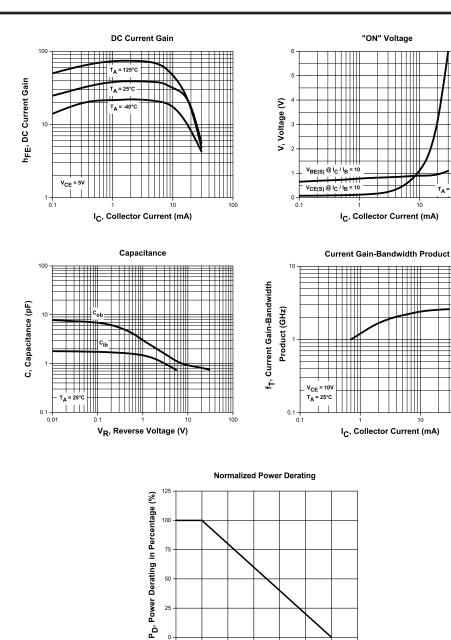
R1 (21-March 2017)

CP617-CM4957 **Typical Electrical Characteristics**



www.centralsemi.com

T_A = 25



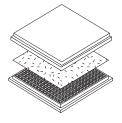
0+0

 T_A, Ambient Temperature (°C)

R1 (21-March 2017)

BARE DIE PACKING OPTIONS



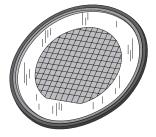


BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- · Environmental regulation compliance
- Customer specific screening
- · Up-screening capabilities

· Custom product packing

Custom bar coding for shipments

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when 1. ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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